

LAYER STACK-UP – ALL DIMENSIONS IN INCHES

		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE
LAYER 1 – TOP SIDE – SIGNAL	.5 oz	0.008	
LAYER 2 – GND PLANE	1 oz		
LAYER 3 – SIGNAL	1 oz	0.007	0.005 / 0.008
LAYER 4 – GND PLANE	1 oz		
LAYER 5 – VCC PLANE	1 oz		
LAYER 6 – SIGNAL	1 oz	0.007	0.005 / 0.008
LAYER 7 – GND PLANE	1 oz		
LAYER 8 – BOTTOM (SECONDARY) SIGNAL	.5 oz	0.008	

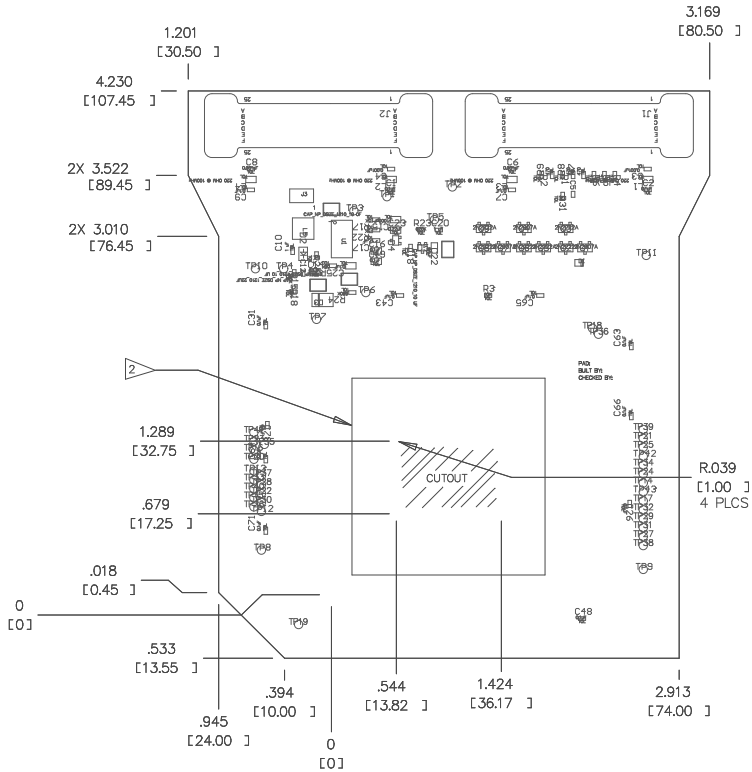
DETAIL A

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES(MILLIMETERS) UNLESS OTHERWISE SPECIFIED
2. THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 170 Tg POLYCLAD OR EQUIVALENT. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B, COLOR: NATURAL.
4. UL RECOGNIZED COMPONENT (ZMW/2) – FLAMMABILITY RATING: 94V-0 DIRECT SUPPORT RATING PER UL796: YES (OPTIONAL MARKING OPTIONAL) TEMPERATURE RATING: 105 DEGREES C MINIMUM.
5. ELECTRICAL TEST MARKINGS SHOULD BE LEGIBLE, PERMANENT AND LOCATED ON THE SECONDARY SIDE OF THE BOARD AND WITHSTAND WAVE SOLDER (LOCATION NOT TO BE UNDER COMPONENTS). 1000 AND 84V-0 FLAMMABILITY RATING SHOULD BE ETCHED ON THE SECONDARY SIDE OF THE BOARD.
6. IONIC CONTAMINATION LEVEL 10 uG/N SQ MAXIMUM.
7. VERIFICATION OF GOLD AND NICKEL PLATING THICKNESS REQUIRED FOR EACH FABRICATION LOT.
8. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH WITH A MINIMUM ANNULAR RING OF .002 INCH.
9. OVERALL BOARD THICKNESS TO BE .063 INCHES +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
10. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
11. MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
12. NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
13. FOIL OUTER OPTIONAL.
14. MARK REVISION LETTER OF PWB. LOCATION AND METHOD OPTIONAL.
15. TEARDROP VIAS AS NECESSARY.
16. SEE DETAIL A FOR IMPEDANCE REQUIREMENTS AND COPPER WEIGHTS

PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES OF THE PWB SHALL BE ELECTROLYTIC IMERSION GOLD, 2 – 6 MICRO-INCHES MINIMUM, OVER 100 MICRO-INCHES OF NICKEL.
2. PLATE INDICATED AREA (SECONDARY SIDE) WITH 0.0001 INCH MINIMUM LOW STRESS NICKEL UNDER 0.00005 MINIMUM GOLD HAVING A HARDNESS OF HVOX014.
3. APPLY LPI SOLDERMASK. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV. COLOR: GREEN.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
5. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.



TOP SIDE VIEW

